

TI Live! BATTERY MANAGEMENT SYSTEMS SEMINAR

JEFF FALIN

RESOLVING BATTERY CHARGING COMMON APPLICATION ISSUES

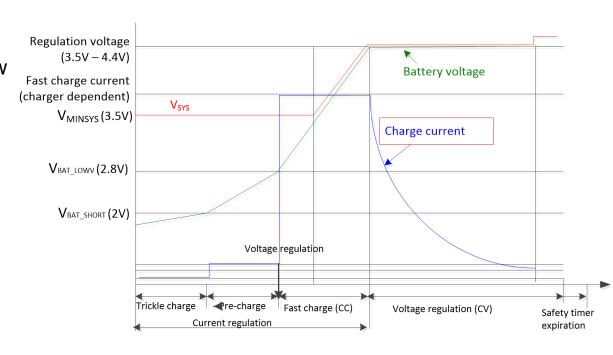


Agenda

- Review of Li-ion battery charging and charger topology
- Most common issues for battery charging:
 - Battery not charging
 - Long charge time
 - High charge currents cause board thermal issues
- Summary

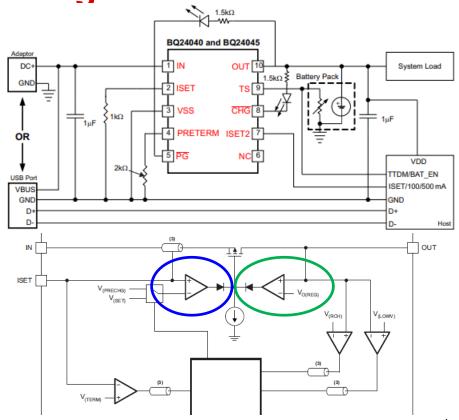
Complete Li-ion battery charging profile

- Trickle charge for very low V_{BAT}
 - 50-100mA
- Pre-charge current when V_{BAT} low
 - Close the protector of deeply discharged battery
 - S/A is % of I_{FAST_CHRG}
 - ~10-20% accuracy typical
- Term current when V_{BAT} = CV
 - Stopping charge to prevent overcharge for long battery life
 - S/A is % of I_{FAST_CHRG}
 - ~10-20% accuracy typical
- ~5-24 hour safety timer
 - Prevent charge of damaged battery
 - S/A fixed or uses external cap



Simple standalone linear charger

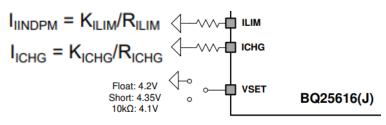
- Asynchronous state machine with analog feedback loops for
 - Constant current regulation
 - Constant voltage regulation
- Comparators for
 - Input protection
 - UVLO
 - Sleep comparators
 - OVP
 - Output short protection
 - TS pin
- Status pin: /CHG, /PG



Benefits and limitations of standalone charger

Benefits

- Simple and no software
- Pin level and/or resistors set charge voltage and currents



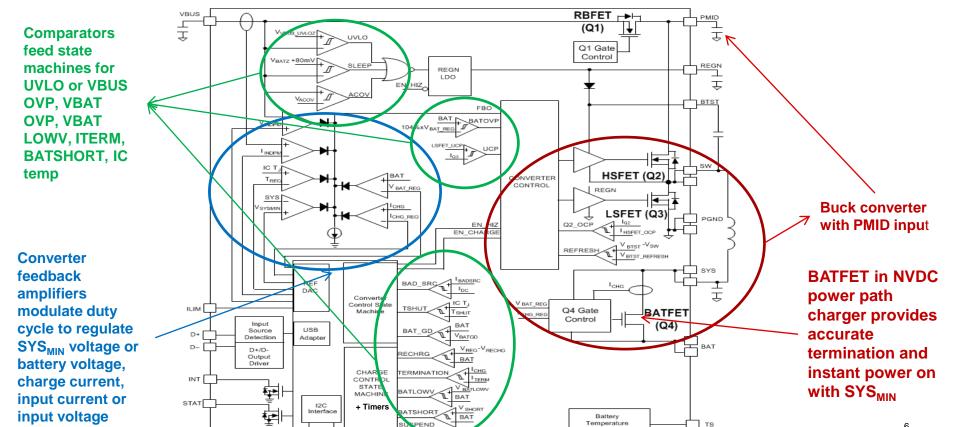
V	ICHC pip cotting ratio	ICHG=K _{ICHG} /R _{ICHG} , VBAT = 3.1V, T _J = -40°C - 85°C	639	677	715	ΑχΩ
K _{ICHG}	ICHG pin setting ratio	$ICHG=K_{ICHG}/R_{ICHG}$, VBAT = 3.8V, T _J = $-40^{\circ}C$ - $85^{\circ}C$	639	677	715	ΑχΩ

Limitations

- Pre-charge/term currents are fixed 10% of fast charge
- Resistor tolerance affects regulation accuracy
- Hardware required to dynamically change I_{CHG}
- Limited status reporting

CHARGING STATE	STAT INDICATOR
Charging in progress (including recharge)	LOW
Charging termination (top off timer may be running)	HIGH
Sleep mode, charge disable, boost mode	HIGH
Charge suspend (input over-voltage, TS fault, safety timer fault or system over-voltage)	Blinking at 1 Hz

Host controlled buck switching charger



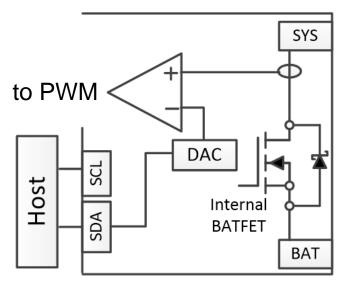
Sensing

Benefits and limitations of host controlled

Benefits

Example from BQ2579x 1s-4s, 5-A charger:

- I²C/SMBus register with high resolution and accuracy (no resistors necessary) set
 - CV: 3 V 18.8 V in 10-mV steps
 - $-I_{PRE}/I_{TERM}$: 40 mA 1 A / 40 mA 2 A in 40-mA steps
 - CC: 10 mA 5 A in 10-mA steps
 - Safety timer: 5 hr, 8 hr, 12 hr, 24 hr
 - Enable/disable: PFM, OOA, ship mode, etc.
- Status/fault registers report operation
 - Loop: CC, CV, I_{INDPM}, V_{INDPM}, T_{REG}
 - Status/Fault: PG, VBUS OVP, VBAT OVP, etc.
- Integrated ADC: V_{BUS}, V_{BAT}, I_{BUS}, I_{BAT},T_{DIE}



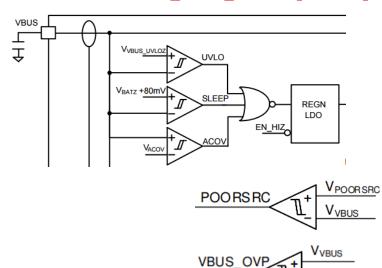
Limitations

Host software required

Most common issue 1: Battery not charging

Not charging: Input protection/control related

 V_{VBUS_OVP}



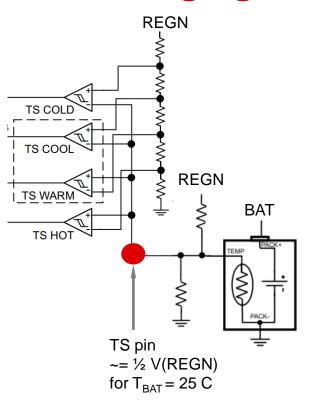
	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
REGN LD	0	•				
V _(REGN)	REGN LDO output voltage	V _(VBUS) = 9 V, I _(REGN) = 40 mA	5.6	6	6.4	V
		V _(VBUS) = 5 V, I _(REGN) = 20 mA	4.7	4.8		V
I _(REGN)	REGN LDO current limit	V _(VBUS) = 9 V, V _(RFGN) = 3.8 V	50			mΑ

(REGN)

Issue	Solution
Input power bad: - sleep mode because VBUS <v(bat) (poor="" +="" -="" bad="" because="" disabled="" or="" overvoltage<="" src="" th="" uvlo="" vbu="" vslp=""><th></th></v(bat)>	
Charge enable (CE) p bit not properly configured	hardware and bit via software
LDO (REGN) voltage below regulation	Reduce loading on LDO to below min allowed

Not charging: Battery safety related

JEITA

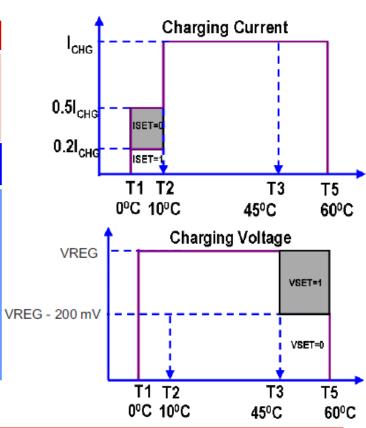


Issue

 Battery temperature outside of safety range

Solution

- Check V(TS)
- Either gauge or charger can monitor not both



Not charging: Timer related

Precharge current limit

Type: RW

EN_TIMER

CHG TIMER[1]

CHG TIMER[0]

3

2

POR: 120mA (3h)
Range : 40mA-2000mA
Fixed Offset : 0mA
Bit Step Size : 40mA

Pre-charge safety timer setting

R/W

R/W

R/W

Type: RW POR: 0b

0h = 2 hrs (default)

1h = 0.5 hrs

-fixed value for all standalone and many I2C chargers For standalone charger with I _{PRE} = % of I _{CHG} per ISET pin, parallel FET and resistor. Increase pre-charger timer available Fast charge timer expired fixed value or capacitor set value for standalone -fixed value for standalone For standalone charger with I _{PRE} = % of I _{CHG} per ISET pin, parallel FET and resistor. Increase pre-charger timer available 1. Identify cause of long charge time.		Issue		Solution		
- fixed value or capacitor set value for standalone charge time. 2. Increase or disable timer for	etting	-fixed value fo standalone ar	or all	I _{PRE} = % of I _{CHG} per ISET pin, use parallel FET and resistor. Increase pre-charger timer if		
nost controlled charges		- fixed value or capacitor set		charge time.2. Increase or disable timer for		
by Softwareby by Watchdog Charging Safety Timer Enable 0 – Disable 1 – Enable (default) 3. Monitor status registers		0 – Disable				
by Softwarehy Fast Charge Timer Setting	by Watchdog by Softwarek	00 – 5 hrs 01 – 8 hrs 10 – 12 hrs (default)		and/or STAT/INT for fault then toggle /CE pin or CE bit to		

Most common issue 2: Long charge time

Long charge time due to watchdog timer expiration

- Host controlled charger I2C registers that could be reset:
 - Input current limit / ILIM pin enable
 - Charge, pre-charge, term current
 - Safety timer
 - Battery regulation/pre-charge voltage
 - JEITA settings
 - Charge enable/disable

	1	1			\
3	WD_RST	R/W	Oh (Reset by: WATCHDOG REG_RST	I2C watch dog timer reset Type : RW POR: 0b 0h = Normal (default) 1h = Reset (this bit goes back to 0 after timer resets)
2-0	WATCHDOG_2:0	R/W	5h	Reset by: REG_RST	Watchdog timer settings Type: RW POR: 101b 0h = Disable 1h = 0.5s 2h = 1s 3h = 2s 4h = 20s 5h = 40s (default) 6h = 80s 7h = 160s

Issue	Solution
I2C watchdog timer bit not periodically pinged causing registers to rese to defaults	 Disable watchdog (not recommended) Modify software to periodically ping the watchdog bit

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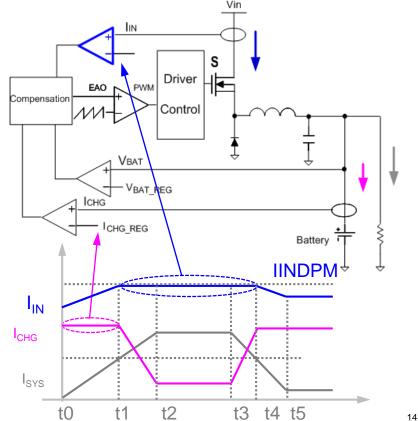
Long charging time due to IINDPM

Issue

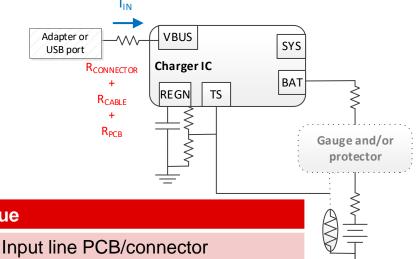
 Input power too low for I(SYS) + I(CHG) because IINDPM setting too low

Solution

- Reduce load on SYS
- Increase power source and IINLIM resistor setting
- Disable ILIM resistor clamp if available (resets after watchdog expires)
- Change IINDPM from D+/Ddetection after USB enumeration



Long charging time due to input side impedance

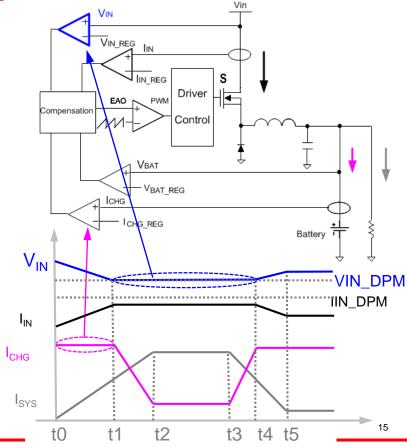


resistances too high

Solution

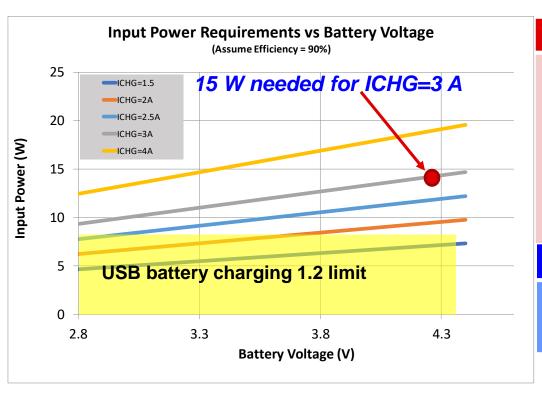
Issue

- Use higher quality connector/cable
- Lower VINDPM threshold
 - Caution: Avoid 100% duty cycle
 - Caution: Avoid overstressing adapter





Long charge time due to input power limitation



Issue

- Input power limited by
 - Legacy USB Adapters (5W/10W)
 - Connector current limit (< 1.8A)
 - Cable IR drop (V=300m Ω * 1.8A)
- Higher battery charging current requires more input power.
 - Up-to 15 W required for 3-A charging.

Solution

- Higher efficiency charger
- High voltage adapter (HVDCP)

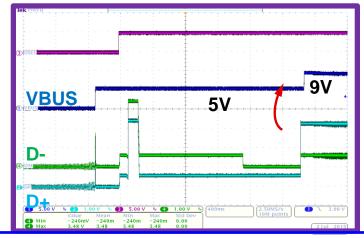
Adjustable high voltage adapters

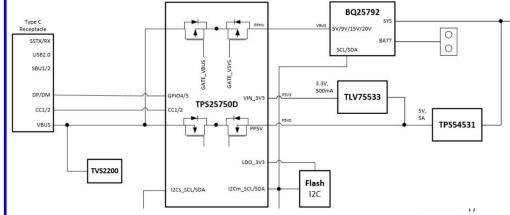
Adjustable HV adapter:

- Compatible with USB 5-V adapter
- Can increase output voltage from 5 V to 7 V/9 V/12 V after handshake
 - Voltage based by using D+/D- voltage signaling.

USB TYPE-C with Power Delivery

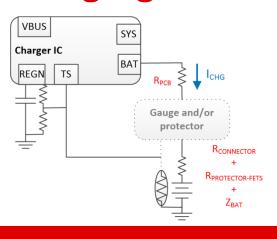
- Profile 1, 10 W \rightarrow 5 V/2 A
- Profile 2, 18 W \rightarrow 5 V/2 A, or 12 V/1.5 A
- Profile 3, 36 W → 5 V/2 A, or 12 V/3 A
- Profile 4, 60 W→5 V/2 A, or 12 V/3 A or 20 V/3 A
- Profile 5, 100 W→5 V/2 A, or 12 V/5 A or 20 V/5 A

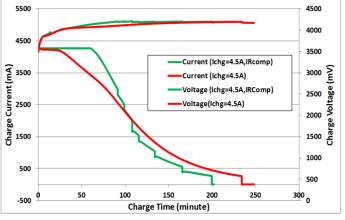






Long charging time due to output side impedance



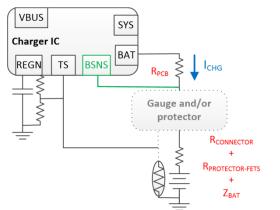


Issue

Battery PCB/connector resistances too high

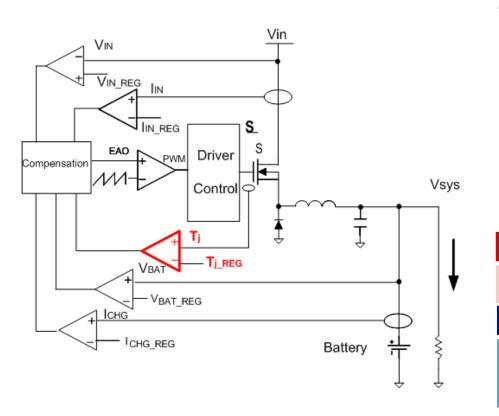
Solution

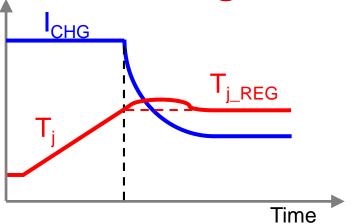
- Increase I_{TERM} current at expense of full charge
- IR Comp: Increase VBATREG to offset $V_{DROP} = I_{BAT} R_{OUT}$
- Choose a charger with remote sense



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Long charging time due to IC thermal regulation





Issue

High temp of IC

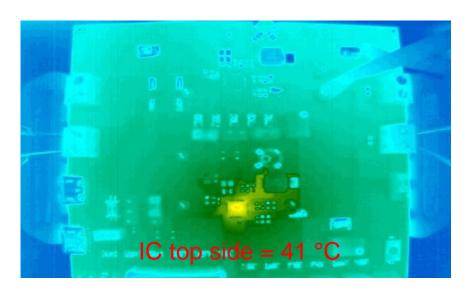
Solution

 Improve PCB layout and heat sinking for the charger

Improve board layout for heatsinking (and lower EMI)

 Use thermal pad connected to internal PGND with vias for heatsinking Top layer Layout priorities for lower EMI: C_{PMID} – IN for buck (OUT for OTG boost) to shunt high freq. 2nd layer PGND on switching noise to GND **PGND** (PGND) Top layer $C_{REGN,} C_{BTST}$ C_{SYS}, C_{BAT} C_{REGN} C_{BTST} C_{PMID} • L1 – adding more R and L not an issue R_{BTST} **PGND** VBUS C_{BUS} V_{sys} **VBUS** Csys High **PGND** frequency Loop BAT **PGND** Common Power GND Point

Long charge time due to board/case overheating



BQ25890 in 4-mm x 4-mm QFN with vias to internal and bottom GND layers

V(VBUS = 9 V, V(BAT)=3.8 V, ICHRG = 3 A

Issue

 Board/case temp exceeds thermal budget requires lower ICHRG

Solution

- Increase number of board layers for heatsinking or add airflow
- Connect pins and/or thermal pads to large copper planes
- More space between heat generating components
- Change to more efficient charger

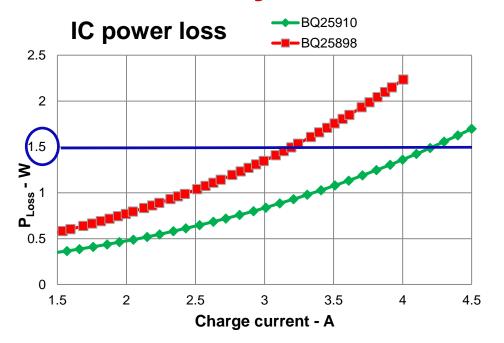
Most common issue 3: Very high ICHRG exceeds board thermal budget

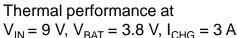
Choose higher efficiency charger for faster, cooler charging

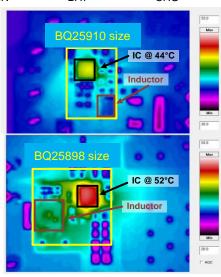
IC	Topology	Inductor DCR (Ω)	High side FET R _{DS(ON)} (Ω)	Low side FET $R_{DS(ON)}$ (Ω)	%eff @ V _{BUS} = 9 V, V _{BAT} = 3.8 V, I _{CHRG} = 3 A	%eff @ V _{BUS} = 5 V, V _{BAT} = 3.8 V, I _{CHRG} = 2 A
BQ2561X	1S buck	10	62	71	89	92.4
BQ25898	1S buck	10	24	12	91.5	93.7
BQ25910	1S 3-level buck	10	32	20	93.5	94.8

- Charger efficiency and therefore power loss for device to dissipate are a function of
 - $-R_{DS(ON)}$ of FETs, both internal and external
 - Inductor with low DCR
 - Appropriate charger topology

Small efficiency increase → higher charge current

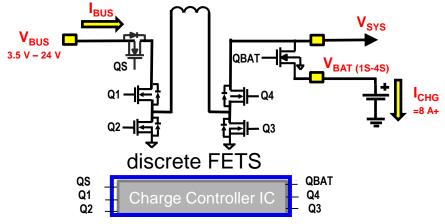




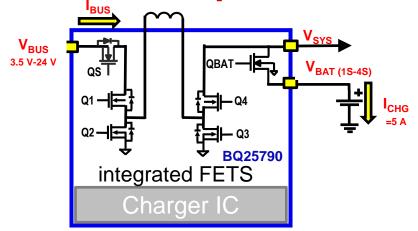


For 1.5-W loss budget, BQ25898 gives $I_{CHG} = 3.2 \text{ A}$ but >3% more efficient BQ25910 can provide 4.2 A of charge current (a **31% increase**) in a 36% smaller solution size due to smaller inductor.

Balance small solution size and thermal performance



Component	Dimensions (mm)	Area (mm²)	Power dissipation
BQ25713QFN	4 x 4	16.00	Minimal
5xFETs	3.3 X 3.3	54.50	Distributed
2xR _{SNS} in 1206	3.2 X 1.6	10.24	Minimal
Total		80.74	



Component	Dimensions (mm)	Area (mm²)	Power dissipation
BQ25790 WCSP	2.9 x 3.3	9.6	One spot
BQ25790 QFN	4.8 x 4.8	23	One spot

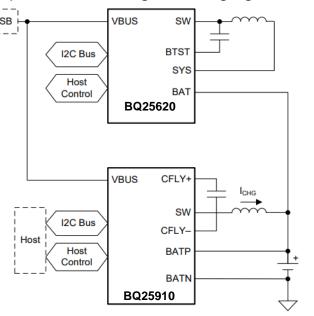
Discrete solution: large areas for thermal dissipation and higher power Integrated solution: small solution size and easy to design but lower power

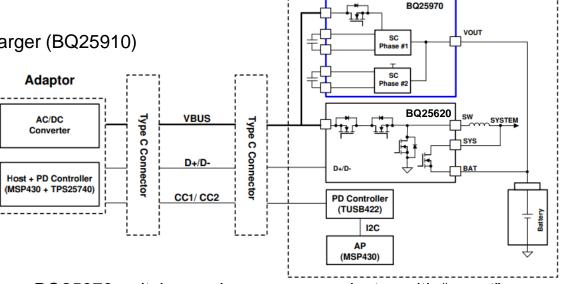
Parallel chargers

 Primary charger (like BQ25620) provides trickle, pre-charge, termination

Secondary, high efficiency 3-level buck charger (BQ25910)

provides fast, higher charging current





- BQ25970 switch cap charger communicates with "smart" adapter/USB-C PD to provide minimum required headroom across pass element
- 97% Efficient power stage for 8-A fast charge

Summary

All issues are solvable!!!

- Battery not charging
 - Account for input protection/operation
 - Protect the battery
 - Design for safety timers
- Long charge (taper) time
 - Optimize IINDPM, VINDPM settings
 - HVDCP adapter
 - Improve heat sinking (and EMI) with good PCB board layout
- Very high ICHRG exceeds board thermal budget
 - Higher efficiency chargers
 - Parallel chargers
- QUESTIONS?



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